

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	217	((cut or scribe or cutting or scribing) with laser) and ((bottom or rear) with (wafer or substrate or workpiece) with (trench or depression or recess or trough))	US-PGPUB; USPAT	OR	ON	2005/09/08 09:46
L2	182	1 and @ad<"20040310"	US-PGPUB; USPAT	OR	ON	2005/09/08 09:12
L3	84	((dicing) with laser) and ((bottom or rear or back) with (wafer or substrate or workpiece) with (trench or depression or recess or trough))	US-PGPUB; USPAT	OR	ON	2005/09/08 08:47
L4	65	3 and @ad<"20040310"	US-PGPUB; USPAT	OR	ON	2005/09/08 08:46
L5	22	4 not 2	US-PGPUB; USPAT	OR	ON	2005/09/08 08:42
L6	63	((dicing) with laser) and ((bottom or rear) with (wafer or substrate or workpiece) with (trench or depression or recess or trough))	US-PGPUB; USPAT	OR	ON	2005/09/08 08:46
L7	52	6 and @ad<"20040310"	US-PGPUB; USPAT	OR	ON	2005/09/08 08:50
L8	43	7 not 5	US-PGPUB; USPAT	OR	ON	2005/09/08 08:46
L9	0	8 not 2	US-PGPUB; USPAT	OR	ON	2005/09/08 08:46
L10	11	((cut or scribe or cutting or scribing or dicing) with laser) and ((bottom or rear or back) with (wafer or substrate or workpiece) with (trench or depression or recess or trough))	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 09:47
L11	4	((cut or scribe or cutting or scribing or dicing) with laser) and ((bottom or rear or back) with (wafer or substrate or workpiece) with (notch))	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 09:49
L12	49	((cut or scribe or cutting or scribing or dicing) with laser) and ((bottom or rear or back) with (wafer or substrate or workpiece) with (notch))	US-PGPUB; USPAT	OR	ON	2005/09/08 09:49
L13	44	12 and @ad<"20040310"	US-PGPUB; USPAT	OR	ON	2005/09/08 08:54
L14	61	((cleave or cleaved or cleaving or splitting or splitted) with laser) and ((bottom or rear or back) with (wafer or substrate or workpiece) with (notch or trench or recess or depression or trough))	US-PGPUB; USPAT	OR	ON	2005/09/08 08:54

L15	58	14 and @ad<"20040310"	US-PGPUB; USPAT	OR	ON	2005/09/08 09:29
L16	41	15 not 2	US-PGPUB; USPAT	OR	ON	2005/09/08 08:54
L17	41	16 not 9	US-PGPUB; USPAT	OR	ON	2005/09/08 08:54
L18	41	17 not 8	US-PGPUB; USPAT	OR	ON	2005/09/08 08:54
L19	9	((("4,729,971") or ("5,185,295") or ("5,851,928") or ("5,923,995") or ("5,998,234") or ("6,117,347") or ("6,136,668") or ("6,271,102") or ("6,399,463") or ("6,420,245"))).PN.	US-PGPUB; USPAT	OR	OFF	2005/09/08 09:16
L20	2	((("6245596") or ("6136668"))).PN.	US-PGPUB; USPAT	OR	OFF	2005/09/08 09:17
L21	512	((cut or scribe or cutting or scribing or dice or dicing or cleave or cleaving or split or splitting or splitted) with laser) and ((bottom or rear or back) with (wafer or substrate or workpiece) with groove)	US-PGPUB; USPAT	OR	ON	2005/09/08 09:50
L22	461	21 and @ad<"20040310"	US-PGPUB; USPAT	OR	ON	2005/09/08 09:47
L23	142	((separating or dividing) with laser) and ((bottom or rear or back) with (wafer or substrate or workpiece) with groove)	US-PGPUB; USPAT	OR	ON	2005/09/08 09:43
L24	122	23 and @ad<"20040310"	US-PGPUB; USPAT	OR	ON	2005/09/08 09:44
L25	48	24 not 22	US-PGPUB; USPAT	OR	ON	2005/09/08 09:44
L26	22	((scribe) with laser) and ((bottom or rear) with (wafer or substrate or workpiece) with (trench or depression or recess or trough))	US-PGPUB; USPAT	OR	ON	2005/09/08 09:46
L27	14	26 and @ad<"20040310"	US-PGPUB; USPAT	OR	ON	2005/09/08 09:47
L28	2	27 not 2	US-PGPUB; USPAT	OR	ON	2005/09/08 09:47
L29	4	((scribe) with laser) and ((bottom or rear or back) with (wafer or substrate or workpiece) with (trench or depression or recess or trough))	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 09:48
L30	1	((scribe) with laser) and ((bottom or rear or back) with (wafer or substrate or workpiece) with (notch))	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 09:49

L31	2	((scribe) with laser) and ((bottom or rear or back) with (wafer or substrate or workpiece) with (notch))	US-PGPUB; USPAT	OR	ON	2005/09/08 09:50
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